Amendments to the Claims

(Canceled) 1 - 14

- (Currently amended) A coaxial via structure in an electronic device 15. carrier adapted to connect power/ground voltage comprising:
- a first generally round conductive track of a first conductive layer on a first surface of a dielectric core[[,]] to a second generally round conductive track of on a second conductive layer in a central portion of said dielectric core, and a third generally round conductive track of a third conductive layer, said conductive layers being separated by dielectric layers;
- a coaxial via structure having at least two first conductive vias for conducting voltage only[[,]] connected to said first and second conductive tracks;
- at least two second conductive vias for conducting voltage only[[,]] connected to said second and third conductive tracks;
- a fourth generally round conductive track of a fourth conductive layer surrounding and on the same level as said first conductive layer;
- a fifth generally round conductive track of a fifth conductive layer surrounding and on the same level as said second conductive layer;
- a sixth generally round conductive track of a sixth conductive layer surrounding and on the same level as said third conductive layer;
- at least two third conductive vias for conducting voltage only[[,]]connected to said fourth and fifth conductive tracks; and

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at least two fourth conductive vias conducting voltage only[[,]] connected to said fifth and sixth conductive tracks.

- The structure as defined in claim 15 wherein 16. (Previously presented) there are at least four vias of either the first set of vias or the second set of vias.
- 17. The structure as defined in claim 15 wherein (Previously presented) the vias of at least one set of vias are symmetrically arranged with respect to each other.
- The structure as defined in claim 15 wherein 18. (Previously presented) the vias of each set of vias are symmetrically arranged with respect to each other.
- The structure as defined in claim 17 wherein 19. (Previously presented) the vias of each set are symmetrically arranged with respect to each other.